# MFF2 Hardware Specification



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#### **Contact Designations and Functions According to ISO 7816-2**

C1	C5
C2	C6
C3	C7
C4	C8

Vcc	Vcc	
RST		Vpp
CLK		I/O
AUX1		AUX2

Vcc	GND
RST	Vpp
CLK	I/O





UICC	MFF2	Designation	Function
C1	Pin 8	Vcc	Supply voltage
C2	Pin 7	RST	Reset input
C3	Pin 6	CLK	Clock input
C4	Pin 5	AUX1/NC	Not used
C5	Pin 1	GND	Ground
C6	Pin 2	Vpp	Programming voltage (not used)
C7	Pin 3	I/O	Input/output for serial communication
C8	Pin 4	AUX2/NC	Not used

#### **Embedding Option – For Handset with Dual SIM slots**



- MFF2 thickness 0.90mm
- Contact assignment same as SIM
- Solder MFF2 to the contact pin

#### **MFF2 DFN8 - Package Characteristic and Pinout Information**



#### **PCB Layout for the MFF**



- The inner C1 to C8 pads are the electrical connection points for MFF1 or MFF2.
- The outer C1 to C8 pads are the electrical connection points for MFF sockets.
- The grey pads in the central area between the C1 to C8 pads are not electrically connected and may serve as anchors to reinforce the mechanical attachment of an MFF to the board.
- Other grey pads beyond the C1 to C8 area may serve as anchors for MFF sockets.
- The rectangular box of 10.50mm by 11.10mm is the recommended clearance zone to accommodate a wide range of MFF sockets.
- A minimum clearance area of 8.05mm by 9.00mm centered at the middle of the contact areas is a minimum to accommodate an MFF socket.

### **SIM Connector for a sample phone**



### **Design of contact points for MFF2**

- Need to update PCB to have additional solder points for the MFF2
- The PCB will be able to handle either SIM slot or MFF2



# Sample photo



## **Thank You!**

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